

Thermal insulation products for building applications — Determination of the tensile bond strength of the adhesive and of the base coat to the thermal insulation material

The European Standard EN 13494:2002 has the status of a
British Standard

ICS 91.100.60

National foreword

This British Standard is the official English language version of EN 13494:2002.

The UK participation in its preparation was entrusted by Technical Committee B/540, Energy performance of materials, components and buildings, to Subcommittee B/540/1, European standards for thermal insulation, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

A list of organizations represented on this subcommittee can be obtained on request to its secretary.

Cross-references

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This British Standard, having been prepared under the direction of the Building and Civil Engineering Sector Policy and Strategy Committee, was published under the authority of the Standards Policy and Strategy Committee on 28 October 2002

Summary of pages

This document comprises a front cover, an inside front cover, the EN title page, pages 2 to 9 and a back cover.

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Amendments issued since publication

Amd. No.	Date	Comments